

1     ABSTRACT OF THE DISCLOSURE

2             A method of engaging electrically conductive test pads on a  
3     semiconductor substrate having integrated circuitry for operability testing  
4     thereof includes: a) providing an engagement probe having an outer  
5     surface comprising a grouping of a plurality of electrically conductive  
6     projecting apexes positioned in proximity to one another to engage a  
7     single test pad on a semiconductor substrate; b) engaging the grouping  
8     of apexes with the single test pad on the semiconductor substrate; and  
9     c) sending an electric signal between the grouping of apexes and test  
10    pad to evaluate operability of integrated circuitry on the semiconductor  
11    substrate. Constructions and methods are disclosed for forming testing  
12    apparatus comprising an engagement probe having an outer surface  
13    comprising a grouping of a plurality of electrically conductive projecting  
14    apexes positioned in proximity to one another to engage a single test  
15    pad on a semiconductor substrate.